

VFQZ35AQ1DDNZ1ZP

- ◆ **Outline(L*W*H): 3.75*3.75*1.5mm**
- ◆ **Good thermal dissipation & optical uniformity**
- ◆ **Materials: ALN and Quartz lenses**



Table of Contents

Product Code Method-----	2
Maximum Rating-----	2
Typical Product Characteristics-----	3
Relative Spectral Power Distribution-----	4
Typical Diagram Characteristics of Radiation-----	4
Relative Spectral Power Distribution-----	5
Dimensions -----	6
Reflow Profile-----	7
Packing-----	8
Test Items and Results of Reliability-----	9

Features

- Forward current: $\leq 100\text{mA}$
- Typical view angle 50% Iv: 120°
- RoHS2.0 and REACH-compliant
- Lens color: water transparent
- ESD level 8 kV(HBM)

Applications

- Disinfection Sterilization
- Bio-Analysis Detection
- Sensor Light
- Medical optical

■ **Product Code Method**

V - F - QZ35 - A - Q1DD - N - Z - 1 - Z- P

① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩

①	②	③	④	⑤
Process Type	Category	Specification	Lens Angle code	Dice wavelength & luminous rank
V: Eutectic process	F: Flip Chip LED	QZ35: 3.75*3.75 mm	A: 120°	Qxxx: UV product

⑥	⑦	⑧	⑨	⑩
Support code	Zener	Cap color ode	Module & Lens code	Current code
N: Substrate Code	Z: Zener	1: Series No	Z: Dispenser	P : 100mA

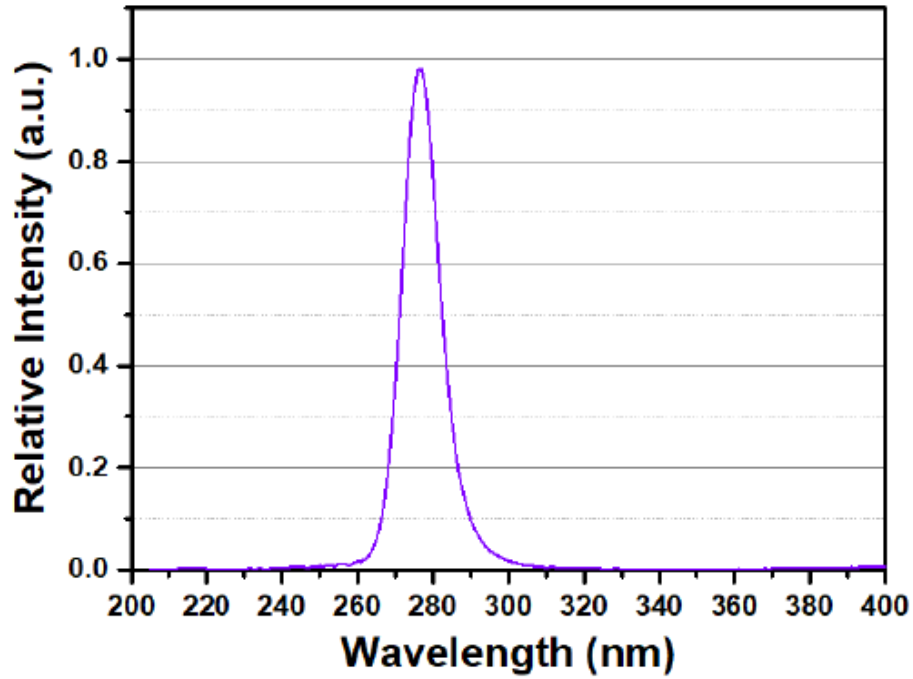
■ **Maximum Rating(Ta=25°C)**

Characteristics	Symbol	Typical	Unit
DC forward current	I _F	100	mA
Operating Temperature Range	TOP	-30-60	°C
Storage Temperature Range	TSTG	-40-100	°C
Thermal Resistance	R _{js}	15	K/W

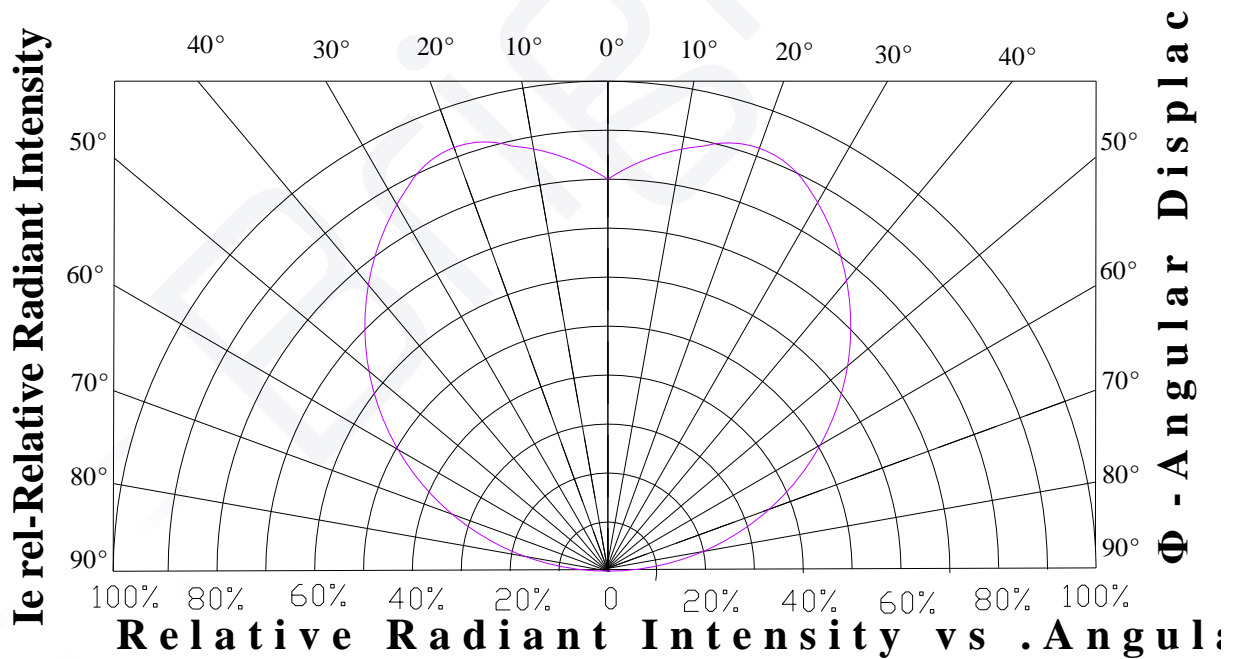
■ Typical Product Characteristics(Ta=25°C)

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Forward Voltage	V_F	5	-	8	V	$I_F=100mA$
Radiant flux (Power)	Φ	8	-	12	Mw	$I_F=100mA$
Peak Wavelength	λ_P	270	275	280	nm	$I_F=100mA$
Spectral Width 50%	$\Delta\lambda$	-	11	-	nm	$I_F=100mA$
Viewing Angle	$2\theta_{1/2}$	-	120	-	Deg	$I_F=100mA$

■ **Relative Spectral Power Distribution**

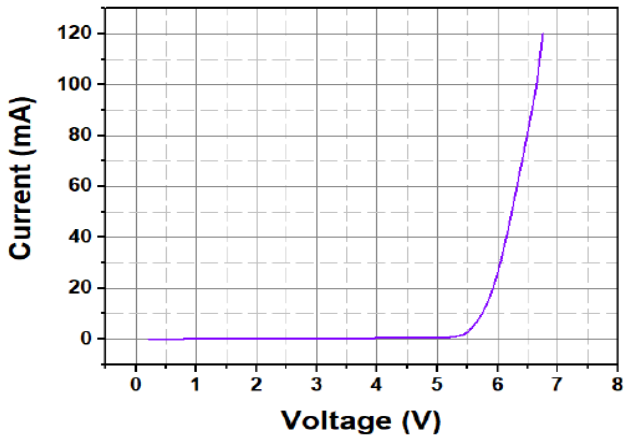


■ **Typical Diagram Characteristics of Radiation**

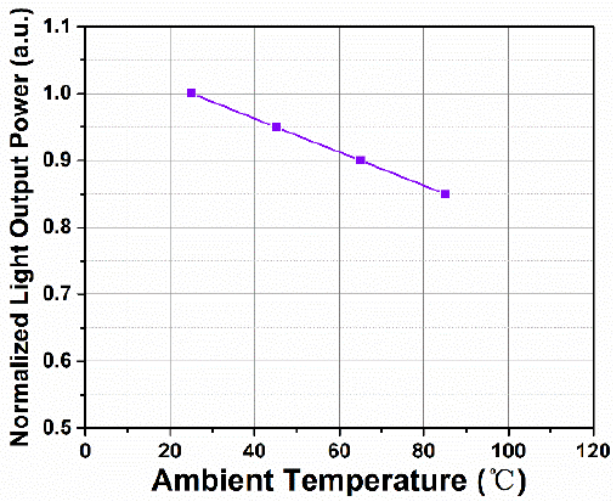


■ Relative Spectral Power Distribution

Forward Current vs. Forward Voltage

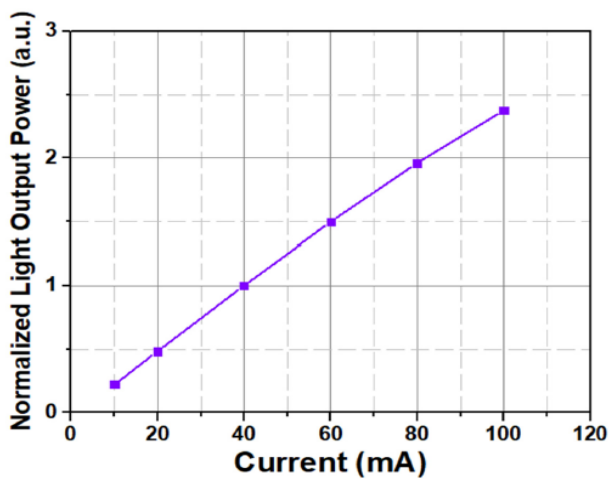


Output Power vs. Ambient Temperature



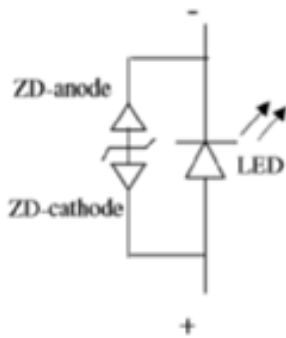
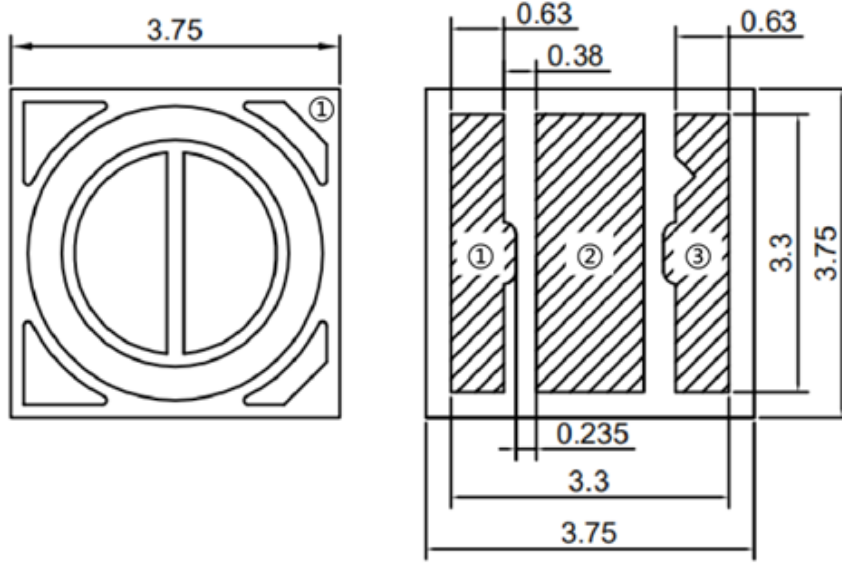
Attenuation: $\Delta 2.5\%/10\text{ }^\circ\text{C}$

Output Power vs. Forward Current



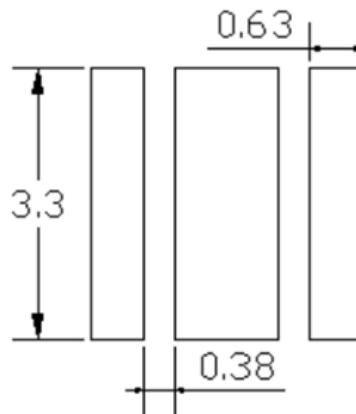
Incremental slope: $\Delta 1\text{ mW}/10\text{ mA}$

■ Dimensions



①	The anode plate welding
②	Thermal pad
③	The cathode plate welding

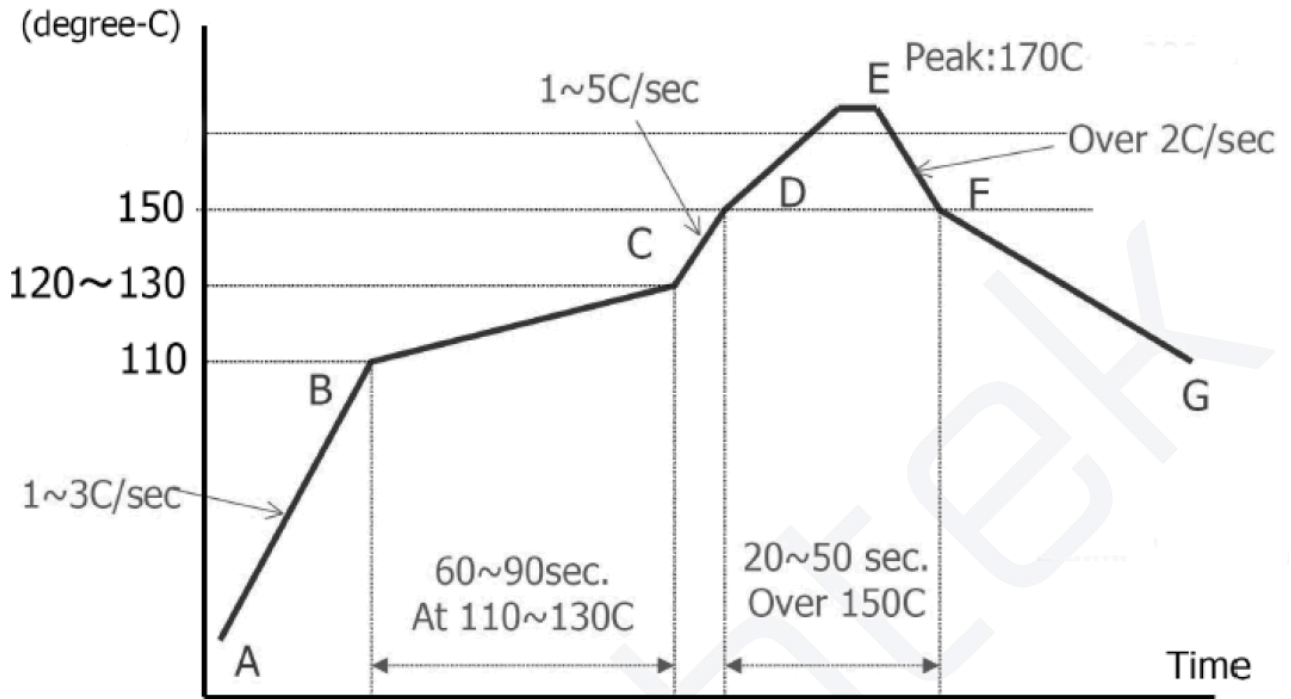
Recommend Pad layout



- Notes:
1. All dimensions are in millimeters
 2. Tolerance is $\pm 0.12\text{mm}$ unless otherwise noted
 3. Specifications are subject to change without notice.
 4. The product height is 1.5 mm

■ Reflow Profile

SMT Reflow Soldering Profile

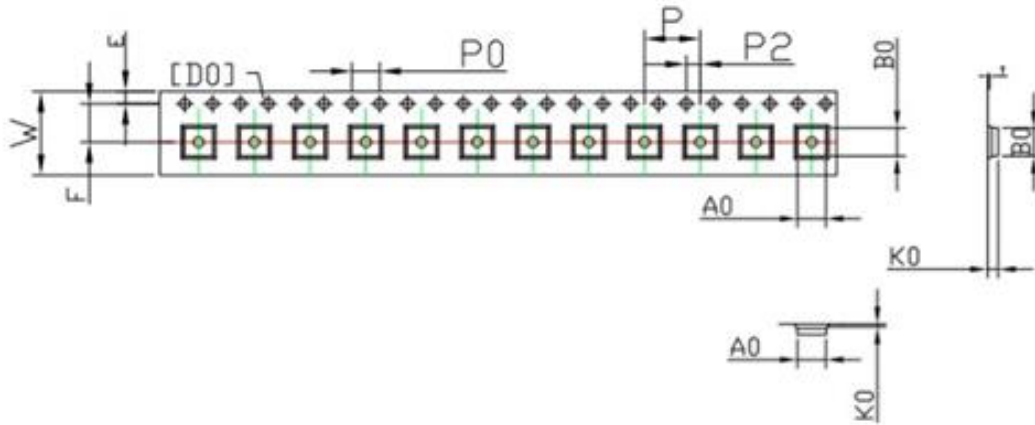


Notes:

Low temperature solder paste shall be used for reflow welding of the patch. The peak temperature shall not be greater than 170 °C, and the peak time shall be controlled at about 20 seconds. Reflux time should not be longer than 5 minutes. Recommend tin bismuth/tin silver bismuth series of solder paste, such as Sn42 / Ag1.0 / Bi57.。

- [1] Reflow welding shall not be performed more than once;
- [2] welding deep uv leds should not be repaired. When repairs are inevitable, appropriate tools must be used.
- [3] during welding, do not apply pressure to the deep uv LED during heating;
- [4] it is recommended to use the convection flow reflow welder above the 7 temperature zone.

■ Packing



Symbol	AO	BO	KO	PO	P	P2
Spoc	3.90 ± 0.1	3.90 ± 0.1	1.60 ± 0.1	4.0 ± 0.10	8.0 ± 0.1	2.00 ± 0.10
Symbol	W	T	E	F	D	D1
Spoc	12.0 ± 0.3	0.30 ± 0.05	1.75 ± 0.10	5.5 ± 0.1	1.5 ± 0.1	1.50 ± 0.10

■ Test Items and Results of Reliability

Test Item	Test Conditions	Duration/ Cycle	Number of Damage	Ac/Re
Resistance to Soldering Heat	Tsld=<170°C, Reflow furnace at 10 °C	1 times	0/100	0/1
Thermal shock	-40°C/15min~120°C /15min	500 cycles	0/35	0/1
Life Test	T _a =25°C I _f =100mA	1000 hrs	0/35	0/1
ESD(HBM)	8KV at 1.5kΩ;100pF	3 times	0/30	0/1

Note: Version updates will not be announced and Brightek will have the final interpretation rights